

ULTRASONIC

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Fully integrated ultrasonic system for thermo- and ultrasonic applications. The combination of the ultrasonic transducer and Tresky's True Vertical Technology™, which guarantees parallelism between chip and substrate as well as controlled bond force at every height, ensures a high quality and reliable bonding. Rotatable ultrasonic unit for easy handling and accurate alignment. 40W, 60 kHz digital generator with continuous power adjustment.

Thermosonic

High power

True Vertical Technology™

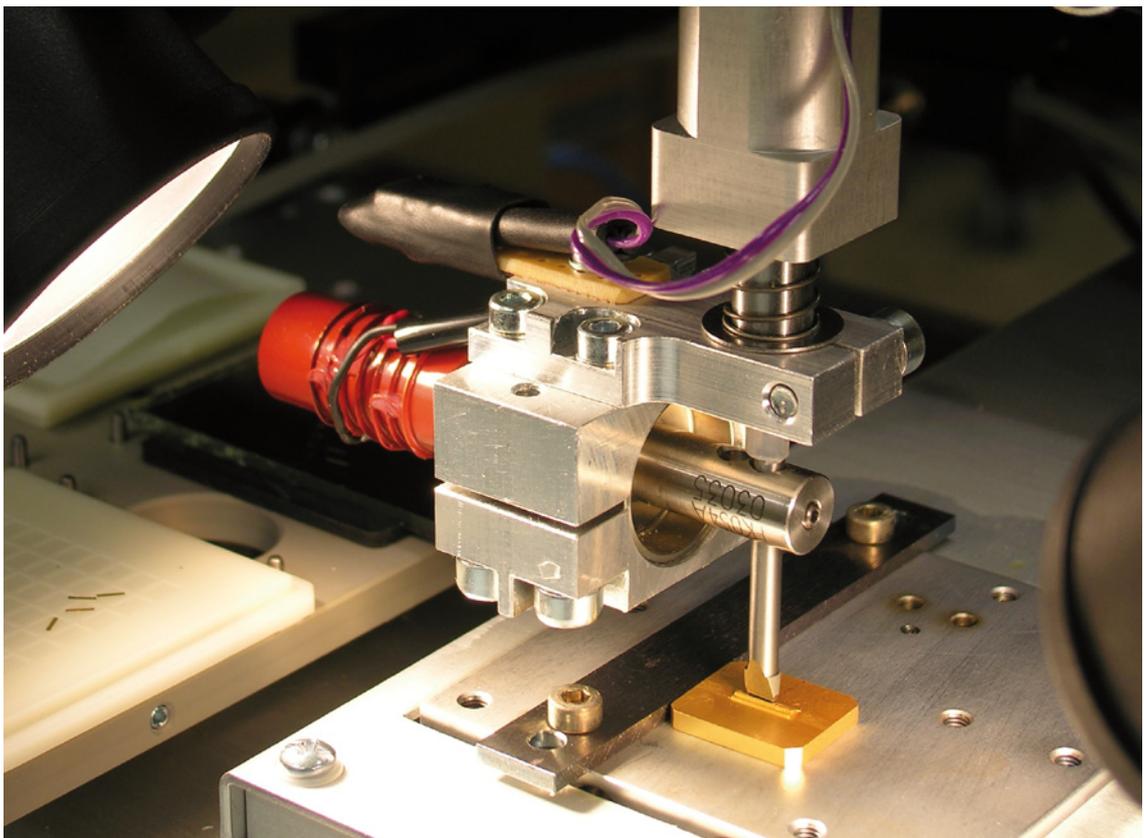
MICRO ASSEMBLY

All T-models can be upgraded.

OPTIONS:

- Various heating plates for substrate
- Inert gas chamber available for critical processes

OPTION



TRESKY